

TIF™100N-50-10F Series thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which effectively enhances the efficiency and life-time of the heat-generating electronic components.

Features

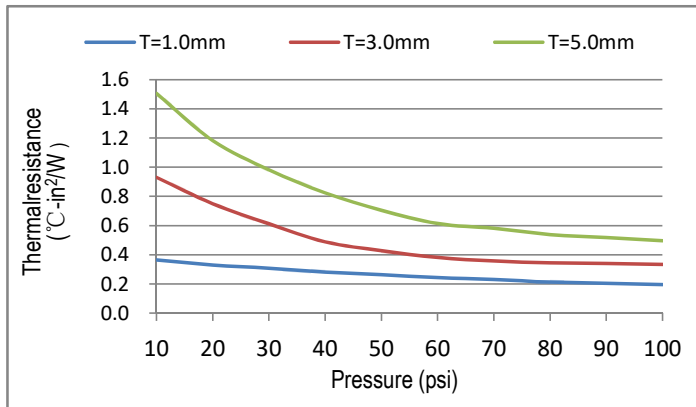
- » Good thermal conductivity
- » Naturally tacky needing no further adhesive coating
- » Soft and Compressible for low stress applications
- » Available in various thickness

Application

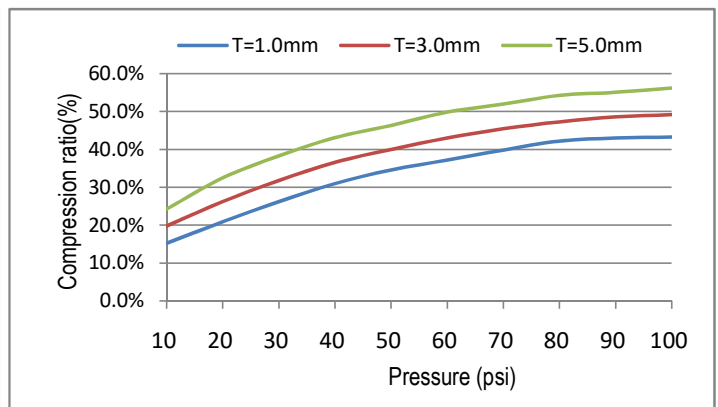
- » Cooling components to the chassis of frame
- » Set Top Box
- » Car Battery & Power Supply
- » Charging Pile
- » LED TV/ Lighting
- » Graphics Card Thermal Module

Typical Properties of TIF™100N-50-10F Series		
Property	Value	Test method
Color	Gray	Visual
Construction	Ceramic filled silicone elastomer	*****
Thickness range	0.020"(0.5mm)~0.200" (5.0mm)	ASTM D374
Hardness (Shore 00)	55±5	ASTM 2240
Density (g/cm ³)	2.1	ASTM D792
Operating Temp	-40~160℃	*****
Dielectric Constant@1MHz	4.7	ASTM D150
Thermal Conductivity (W/mK)	5.0	ASTM D5470
	5.0	ISO22007-2
Flame Rating	94 -V0	UL E331100

Pressure vs. Thermal Resistance



Pressure vs. Compression Ratio



Product Specification

Product Thicknesses: 0.020-inch to 0.200-inch (0.5mm to 5.0mm) **Product Sizes:** 8" x 16"(203mm x 406mm)

Individual die cut shapes and custom thickness can be supplied. Please contact us for confirming

Safe disposal method does not require special protection. The storage condition is low temperature and dry, away from open fire and away from direct sunlight. For detailed method, please refer to the product material safety data sheet.

